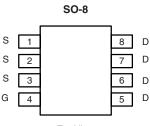


COMPLIANT

Vishay Siliconix

# N-Channel 75-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω <b>)</b>	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
75	0.0098 at V <sub>GS</sub> = 10 V	20.5	36 nC		



Top View

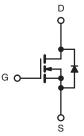
Ordering Information: Si4108DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

#### **FEATURES**

- Halogen-free
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested

#### **APPLICATIONS**

- Primary Side Switch
- Half Bridge
- Intermediate Bus Converter



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATIN</b>	I <b>GS</b> T <sub>A</sub> = 25 °C,	unless otherwise	noted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	75	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
	T <sub>C</sub> = 25 °C		20.5		
Continuous Drain Current (T <sub>1</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	16.4		
Continuous Drain Current (1) = 150°C)	T <sub>A</sub> = 25 °C	D	13.8 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		11.1 <sup>b, c</sup>	Α	
Pulsed Drain Current		I <sub>DM</sub>	60	A	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		6.5		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	Is	3 <sup>b, c</sup>		
Single Pulse Avalanche Current L = 0.1 mH		I <sub>AS</sub>	32		
		E <sub>AS</sub>	51.2	mJ	
	T <sub>C</sub> = 25 °C		7.8		
Maximum Power Discinction	T <sub>C</sub> = 70 °C	P <sub>D</sub>	5	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	'D	3.6 <sup>b, c</sup>	VV	
	T <sub>A</sub> = 70 °C		2.3 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature)			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	29	35	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	13	16		

Notes:

a. Based on  $T_C = 25 \ ^{\circ}C$ .

b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 80 °C/W.



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SPECIFICATIONS $T_J = 25 \ ^{\circ}C$ ,	unless othe	erwise noted					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ V, $I_D = 250$ $\mu$ A	75			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		71.5		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	η = 230 μΑ		- 8.9			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	2		4	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 75 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
		$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10$ V, $V_{GS} = 10$ V	30			А	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 13.8 \text{ A}$		0.0082	0.0098	Ω	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 13.8 A		23		S	
Dynamic <sup>b</sup>	<u> </u>						
Input Capacitance	C <sub>iss</sub>			2100			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 38 V, V <sub>GS</sub> = 0 V, f = 1 MHz		290		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			96			
Total Gate Charge	Qg			36	54		
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = 38 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 13.8 A		10.8		nC	
Gate-Drain Charge	Q <sub>gd</sub>			10			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.22	1.1	2.2	Ω	
Turn-on Delay Time	t <sub>d(on)</sub>			15	23		
Rise Time	t <sub>r</sub>	$V_{DD} = 38 \text{ V}, \text{ R}_{\text{I}} = 3.5 \Omega$		12	18		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 11.1 \text{ A}, \text{ V}_{\text{GEN}} = 8 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		22	33		
Fall Time	t <sub>f</sub>	-		8	16		
Turn-On Delay Time	t <sub>d(on)</sub>			13	25	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 38 \text{ V}, \text{ R}_{\text{I}} = 3.5 \Omega$		11	22		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 11.1 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		23	40		
Fall Time	t <sub>f</sub>	Ŭ		9	18		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			6.5	A	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				60		
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 11.1 A		0.80	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	-		35	53	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			49	75	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^\circ\text{C}$		26	1	1	
Reverse Recovery Rise Time	t <sub>b</sub>			9		ns	

Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %

b. Guaranteed by design, not subject to production testing.

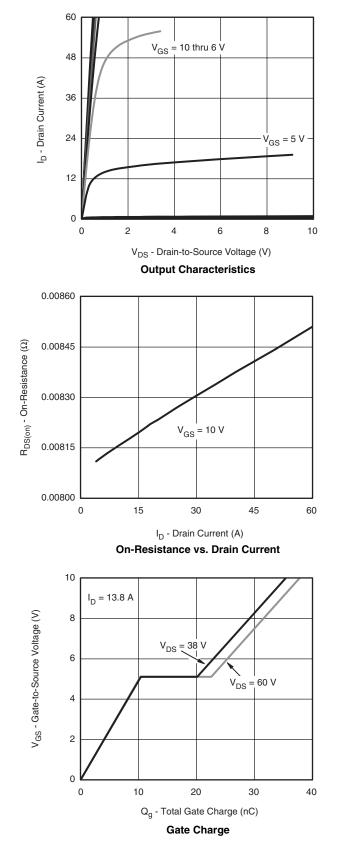
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

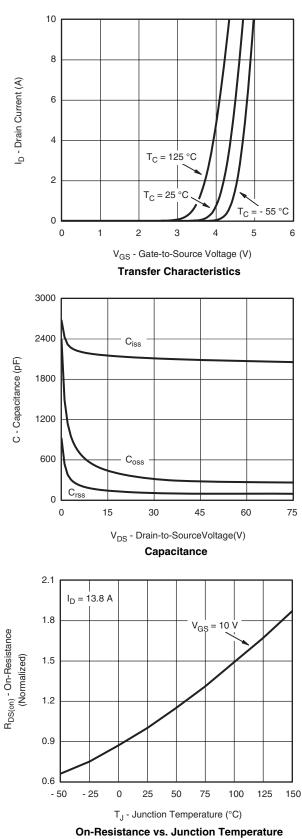


Si4108DY

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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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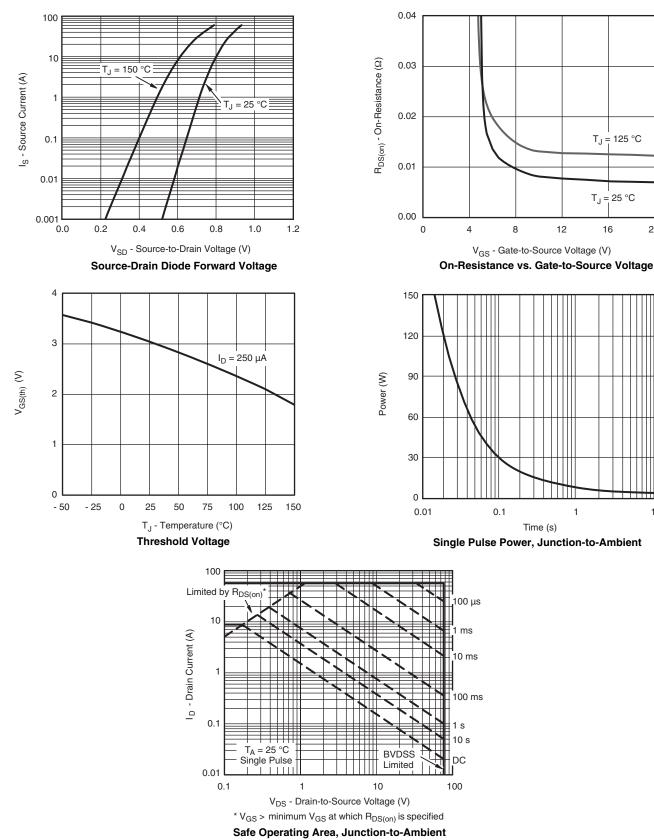
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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

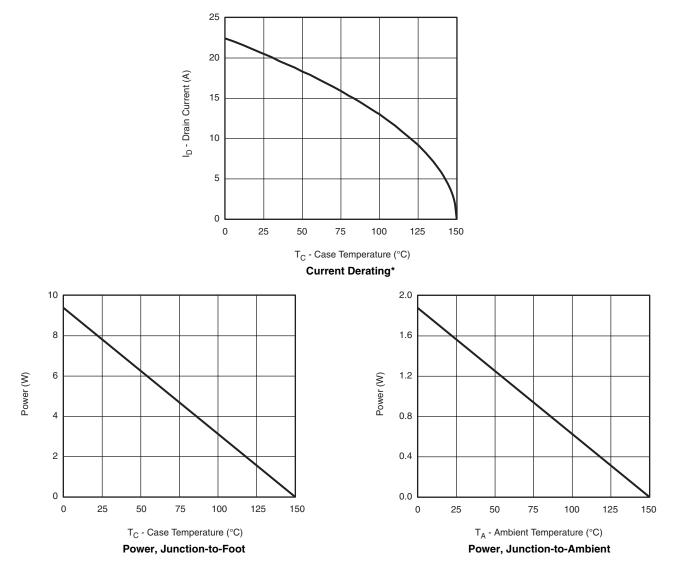


**New Product** 



## Si4108DY Vishay Siliconix

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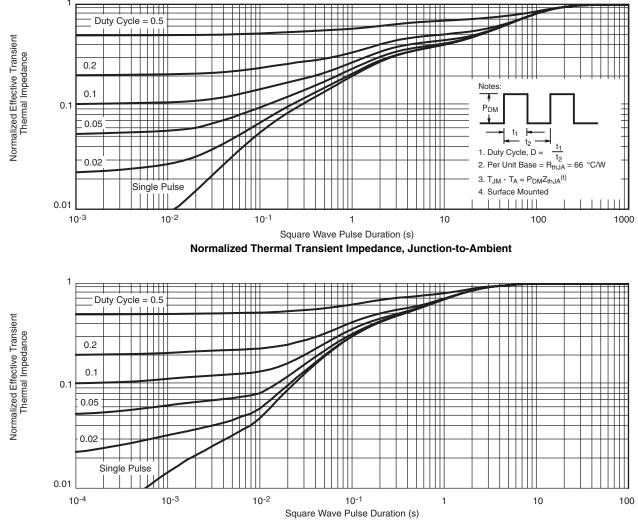


\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 175$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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## Vishay Siliconix

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?68635.



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